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APPLICATION DATA SHEET

Note: If more information is needed please call for a technical data sheet.

PRODUCT: ARV5065 - Series 50 Firm, Urethane Foam Tape w/ PSA

PRODUCT DESCRIPTION: Typical uses for foam tape include BSR applications that require both sound dampening and moderate abrasion resistance. Foam tape is often used to span larger gaps between mating components, such as in a headliner assembly. Available in a variety of types, densities, thicknesses, and custom high-performance adhesive systems, foam tape is highly versatile. For applications requiring additional abrasion resistance, films may be laminated to the composite.

PROPERTY	TEST METHOD	VALUE
PHYSICAL		
Standard Color (code)		Black (04)
Compression Set, % max.	Test D @ 73° F (23°C)	5
	Test D @ 158° F (70°C)	10
	Autoclaved 5hrs @ 250°F (121°C)	5
TEMPERATURE RESISTANCE		
Recommended Constant Use, max.		194°F (90°C)
Recommended Intermittent Use, max.		250°F (121°C)
FLAMMABILITY AND OUTGASSING		
Flammability	MVSS 302 (Pass ≥)	

PRODUCT: Low Fogging Adhesive Transfer Tape
 Note: The adhesive system of this composite can be customized for maximum performance to the individual application requirements.

ADHESIVE: 5.0 mils #300MP Acrylic Adhesive

TYPICAL PHYSICAL PROPERTIES AND PERFORMANCE CHARACTERISTICS:

Surface	15 Minute Dwell		72 Hour Dwell		72 Hour Dwell @ 158°F	
	Oz./In.	N/100 mm	Oz./In.	N/100 mm	Oz./In.	N/100 mm
Stainless Steel	102	112	131	143	166	182
ABS	NA	NA	93	102	78	85

ENVIRONMENTAL PERFORMANCE:

Temperature Resistance: Short Term: 250°F (121°C).
 Humidity Resistance: No adverse effect on the bond after exposure to 100% relative humidity at 100°F (38°C).

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